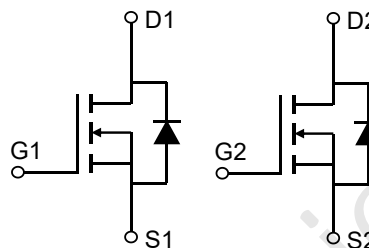


Description

Features

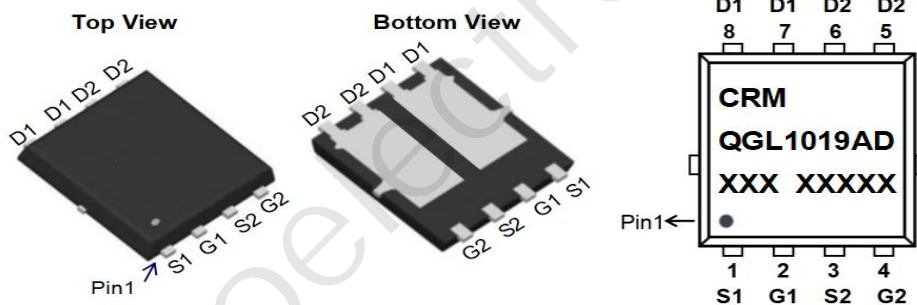
- 100V, 20A
- $R_{DS(ON)}$ Typ = 22mΩ @ $V_{GS} = 10V$
- $R_{DS(ON)}$ Typ = 27.5mΩ @ $V_{GS} = 4.5V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_d s TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQGL1019AD	CRMQGL1019AD	PDFN3.3x3.3-8L-D	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	100	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	20
		$T_C = 100^\circ C$	12
I_{DM}	Pulsed Drain Current ⁽¹⁾	80	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	36	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	20
$R_{\theta JC}$	Thermal Resistance, Junction to Case	6.25	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.8	2.4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 10A	-	22	28.6	mΩ
		V _{GS} = 4.5V, I _D = 8A	-	27.5	35.8	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	-	660	-	pF
C _{oss}	Output Capacitance		-	375	-	pF
C _{rss}	Reverse Transfer Capacitance		-	21	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 50V, I _D = 10A	-	25	-	nC
Q _{gs}	Gate Source Charge		-	6	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 50V I _D = 10A, R _{GEN} = 3Ω	-	14	-	ns
t _r	Turn-On Rise Time		-	12	-	ns
t _{d(off)}	Turn-Off DelayTime		-	23	-	ns
t _f	Turn-Off Fall Time		-	6	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	96	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 10A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 10A, di/dt = 100A/us	-	50	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	90	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=50V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=12A
 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Test Circuit

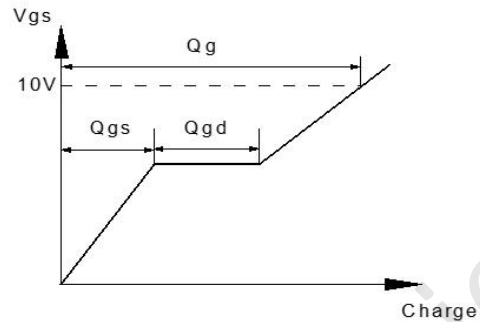
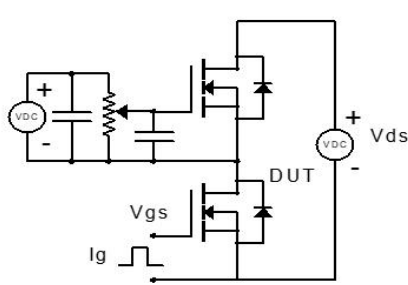


Figure 1: Gate Charge Test Circuit & Waveform

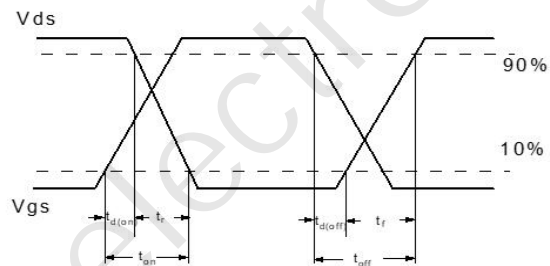
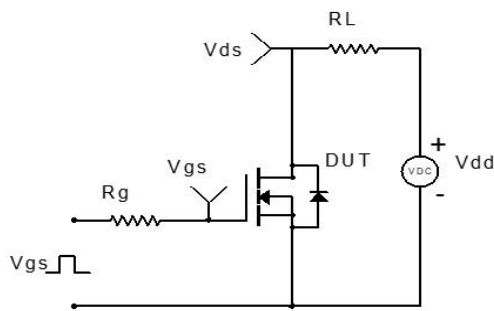


Figure 2: Resistive Switching Test Circuit & Waveform

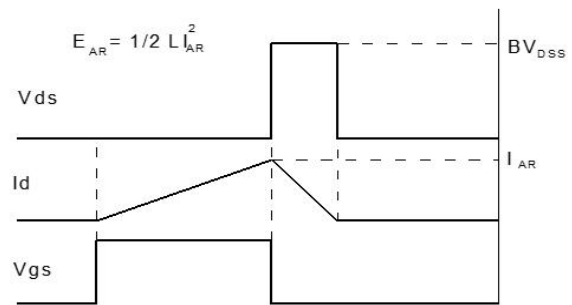
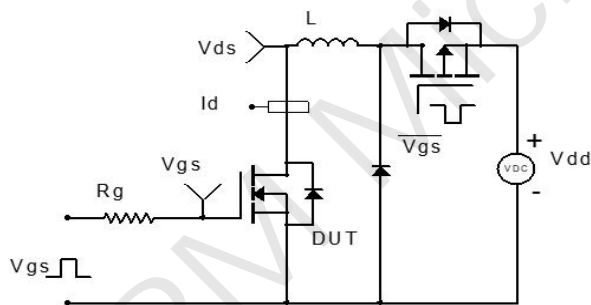


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

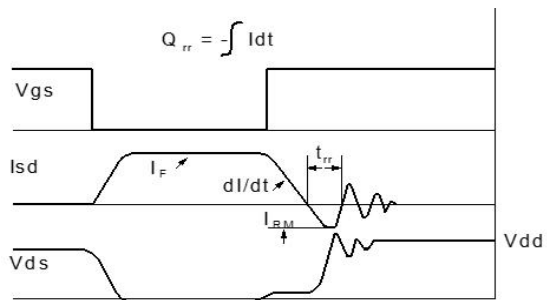
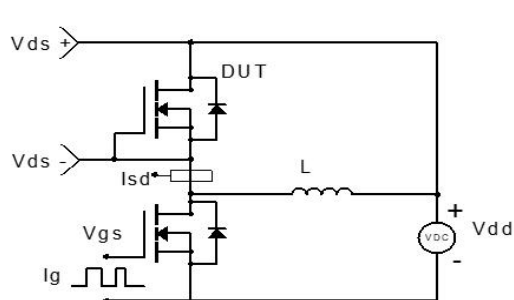
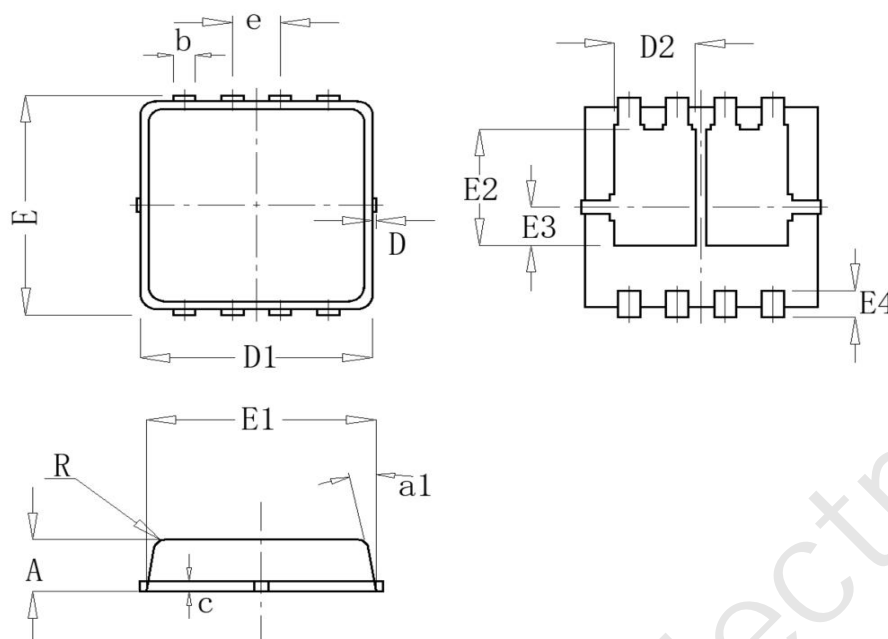


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3.3x3.3-8L-D)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.750	0.780	0.810
* b	—	0.300	0.350
c	—	0.152	—
* D	0.000	0.050	0.100
D1	3.120	3.150	3.180
* D2	—	1.050	—
* E	3.200	3.300	3.400
E1	3.090	3.120	3.150
E2	—	1.750	—
E3	—	0.575	—
* E4	0.300	0.400	0.500
R	—	0.150	—
* e	0.65BSC		
a1°	—	12°	—

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